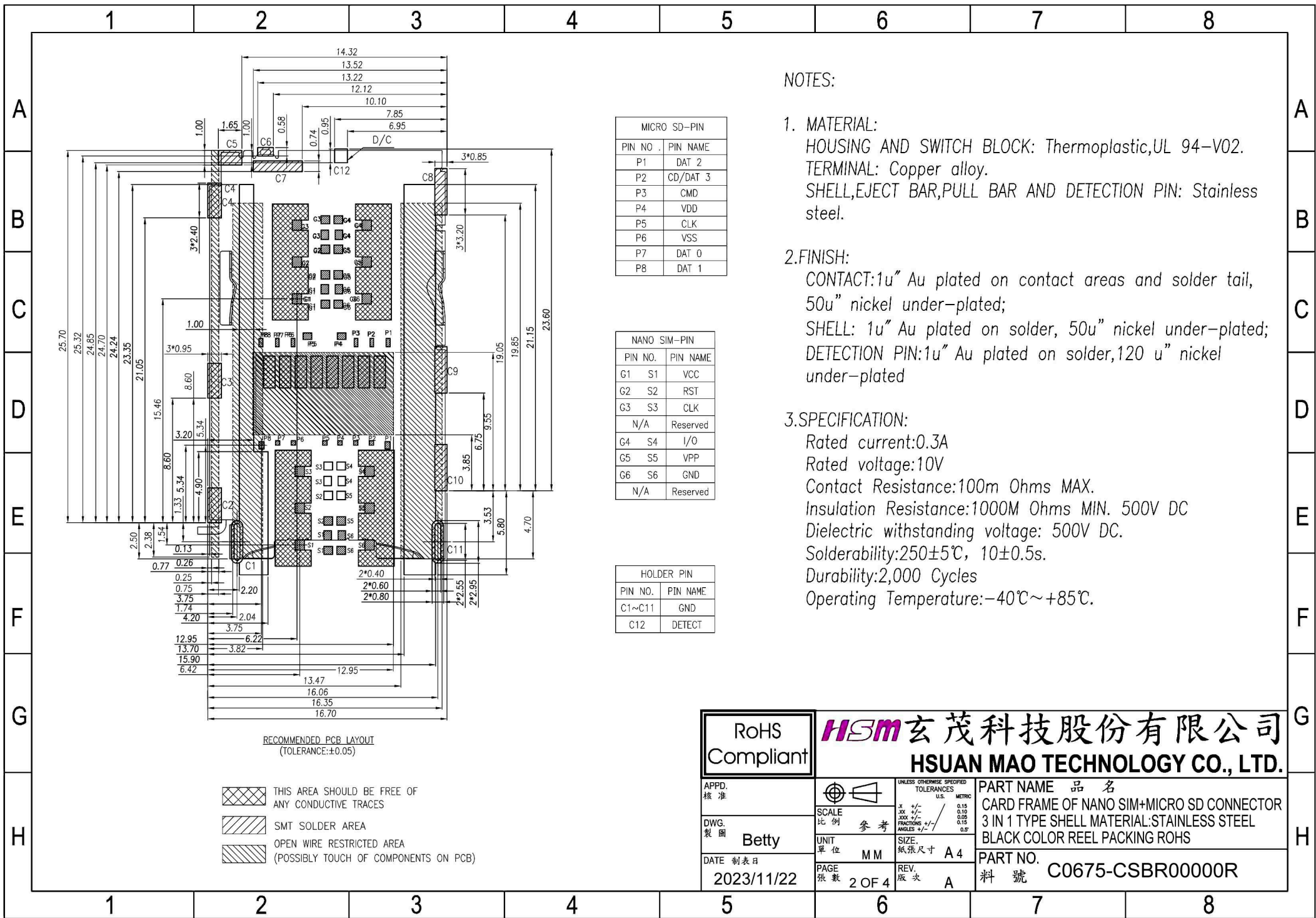


RoHS Compliant **HSM** 玄茂科技股份有限公司
HSUAN MAO TECHNOLOGY CO., LTD.

APPD. 核准		UNLESS OTHERWISE SPECIFIED TOLERANCES	PART NAME 品名
DWG. 製圖	Betty	SCALE 比例 參考	CARD FRAME OF NANO SIM+MICRO SD CONNECTOR
DATE 制表日	2023/11/22	UNIT 單位	3 IN 1 TYPE SHELL MATERIAL: STAINLESS STEEL
		PAGE 張數	BLACK COLOR REEL PACKING ROHS
			PART NO.
			料號 C0675-CSBR00000R



NOTES:

- 1. MATERIAL:**
 HOUSING AND SWITCH BLOCK: Thermoplastic,UL 94-V02.
 TERMINAL: Copper alloy.
 SHELL,EJECT BAR,PULL BAR AND DETECTION PIN: Stainless steel.
- 2.FINISH:**
 CONTACT:1u" Au plated on contact areas and solder tail, 50u" nickel under-plated;
 SHELL: 1u" Au plated on solder, 50u" nickel under-plated;
 DETECTION PIN:1u" Au plated on solder,120 u" nickel under-plated
- 3.SPECIFICATION:**
 Rated current:0.3A
 Rated voltage:10V
 Contact Resistance:100m Ohms MAX.
 Insulation Resistance:1000M Ohms MIN. 500V DC
 Dielectric withstanding voltage: 500V DC.
 Solderability:250±5°C, 10±0.5s.
 Durability:2,000 Cycles
 Operating Temperature:-40°C~+85°C.

MICRO SD-PIN	
PIN NO.	PIN NAME
P1	DAT 2
P2	CD/DAT 3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT 0
P8	DAT 1

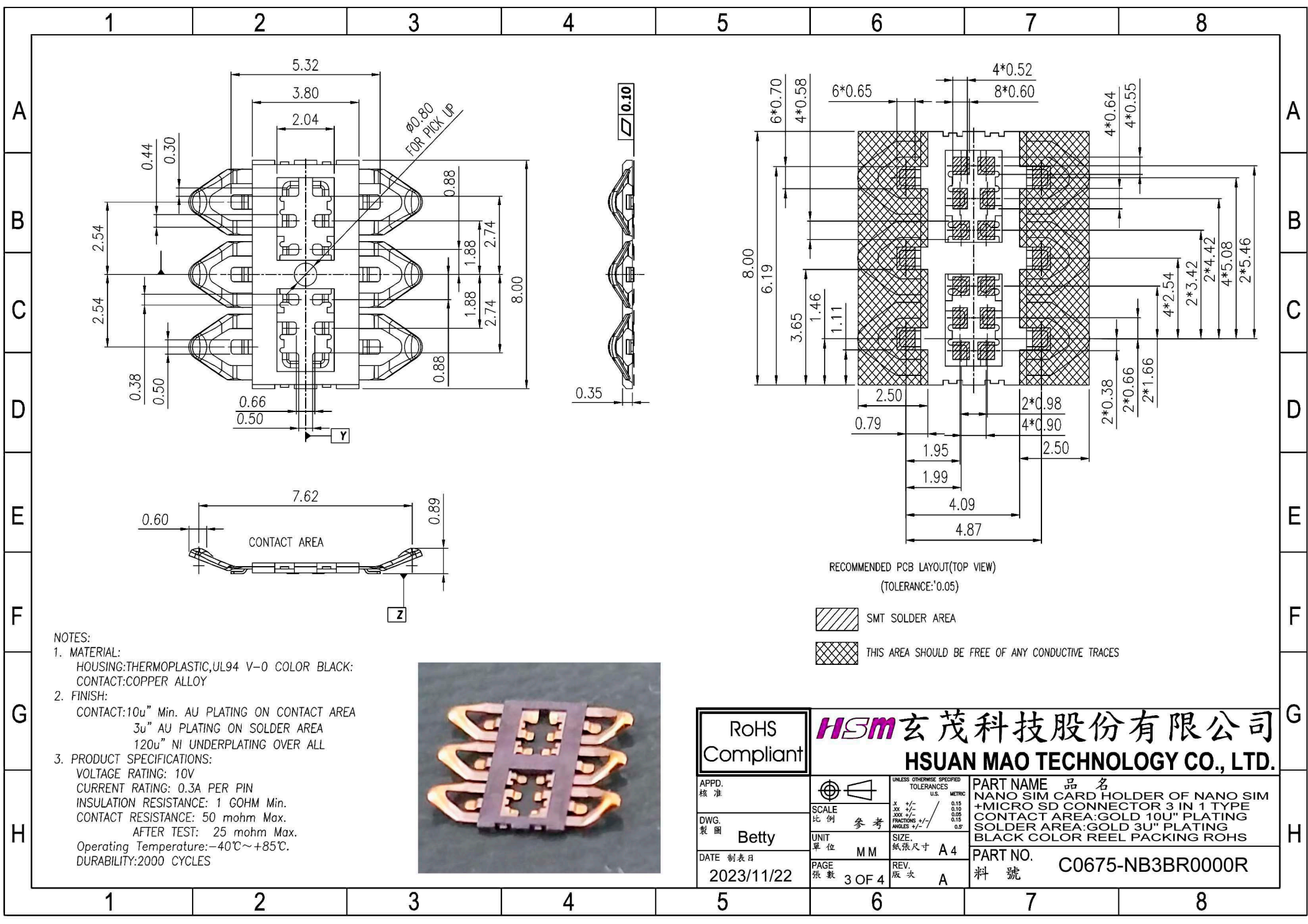
NANO SIM-PIN		
PIN NO.	S1	PIN NAME
G1	S1	VCC
G2	S2	RST
G3	S3	CLK
N/A		Reserved
G4	S4	I/O
G5	S5	VPP
G6	S6	GND
N/A		Reserved

HOLDER PIN	
PIN NO.	PIN NAME
C1~C11	GND
C12	DETECT

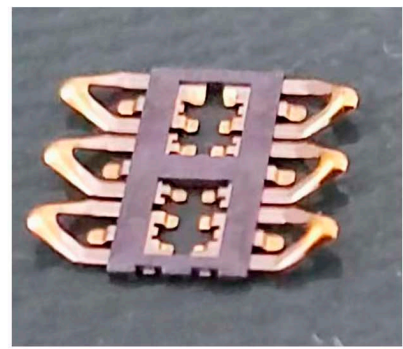
RECOMMENDED PCB LAYOUT
(TOLERANCE:±0.05)

- THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
- SMT SOLDER AREA
- OPEN WIRE RESTRICTED AREA (POSSIBLY TOUCH OF COMPONENTS ON PCB)

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APPD. 核准		UNLESS OTHERWISE SPECIFIED TOLERANCES	PART NAME 品名
DWG. 製圖 Betty	SCALE 比例 參考	METRIC U.S.	CARD FRAME OF NANO SIM+MICRO SD CONNECTOR
DATE 制表日 2023/11/22	UNIT 單位 MM	X +/- 0.15 XX +/- 0.10 XXX +/- 0.05 FRACTIONS +/- 0.15 ANGLES +/- 0.5	3 IN 1 TYPE SHELL MATERIAL:STAINLESS STEEL BLACK COLOR REEL PACKING ROHS
	PAGE 張數 2 OF 4	SIZE. 紙張尺寸 A 4	PART NO. 料號 C0675-CSBR00000R
		REV. 版次 A	



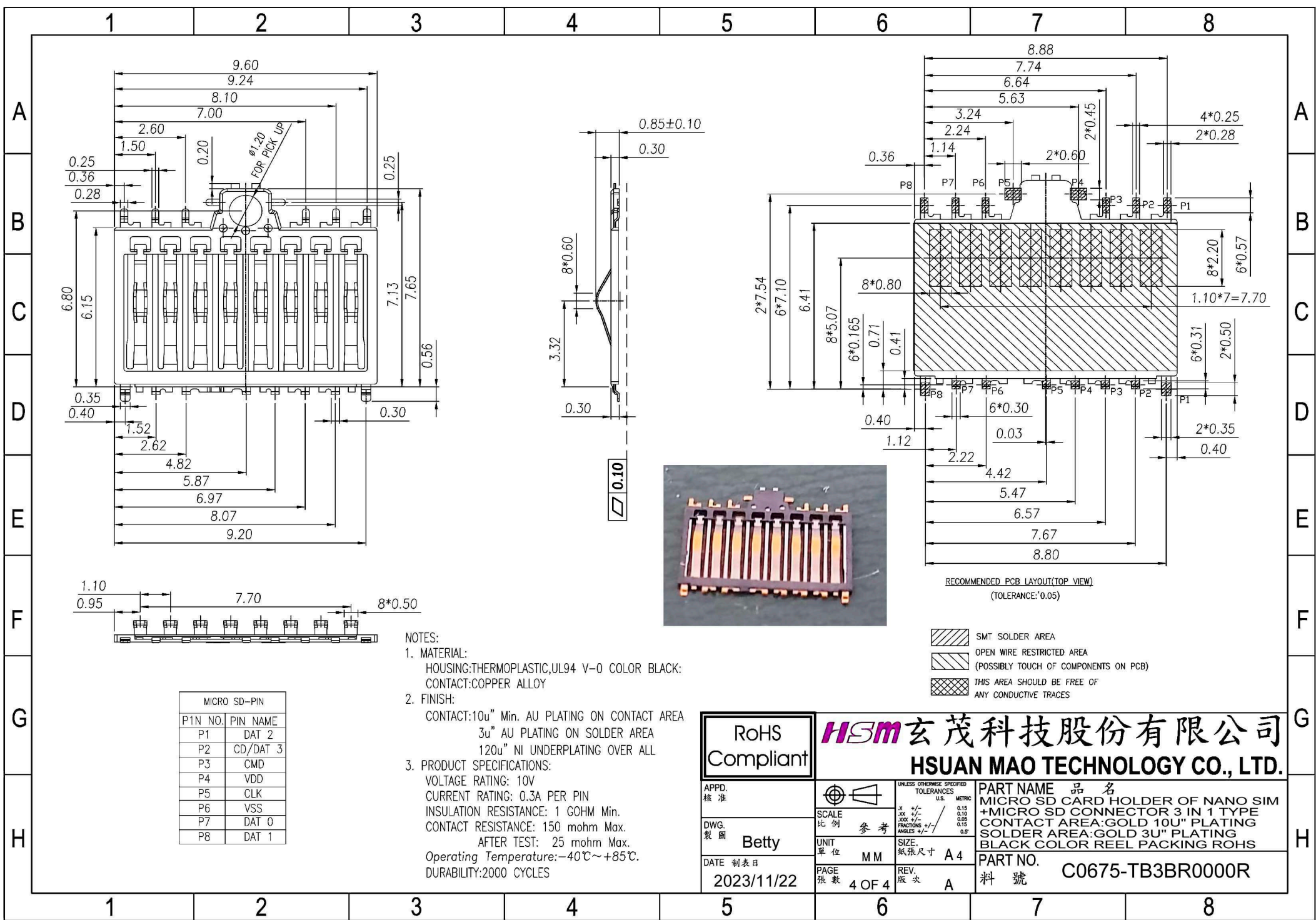
- NOTES:
- MATERIAL:
HOUSING:THERMOPLASTIC,UL94 V-0 COLOR BLACK;
CONTACT:COPPER ALLOY
 - FINISH:
CONTACT:10u" Min. AU PLATING ON CONTACT AREA
3u" AU PLATING ON SOLDER AREA
120u" NI UNDERPLATING OVER ALL
 - PRODUCT SPECIFICATIONS:
VOLTAGE RATING: 10V
CURRENT RATING: 0.3A PER PIN
INSULATION RESISTANCE: 1 GOHM Min.
CONTACT RESISTANCE: 50 mohm Max.
AFTER TEST: 25 mohm Max.
Operating Temperature:-40°C~+85°C.
DURABILITY:2000 CYCLES



RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE:0.05)

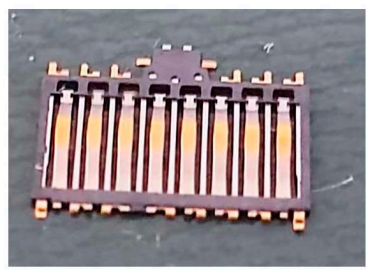
- SMT SOLDER AREA
- THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准		UNLESS OTHERWISE SPECIFIED TOLERANCES	PART NAME 品名
DWG. 製圖	Betty	METRIC U.S.	NANO SIM CARD HOLDER OF NANO SIM +MICRO SD CONNECTOR 3 IN 1 TYPE
DATE 制表日	2023/11/22	SCALE 比例 參考	CONTACT AREA:GOLD 10U" PLATING
		UNIT 單位	SOLDER AREA:GOLD 3U" PLATING
		PAGE 張數	BLACK COLOR REEL PACKING ROHS
		REV. 版次	PART NO. 料號
			C0675-NB3BR0000R



RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE:±0.05)

- SMT SOLDER AREA
- OPEN WIRE RESTRICTED AREA
(POSSIBLY TOUCH OF COMPONENTS ON PCB)
- THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES



- NOTES:
1. MATERIAL:
HOUSING:THERMOPLASTIC,UL94 V-0 COLOR BLACK;
CONTACT:COPPER ALLOY
 2. FINISH:
CONTACT:10u" Min. AU PLATING ON CONTACT AREA
3u" AU PLATING ON SOLDER AREA
120u" NI UNDERPLATING OVER ALL
 3. PRODUCT SPECIFICATIONS:
VOLTAGE RATING: 10V
CURRENT RATING: 0.3A PER PIN
INSULATION RESISTANCE: 1 GOHM Min.
CONTACT RESISTANCE: 150 mohm Max.
AFTER TEST: 25 mohm Max.
Operating Temperature:-40°C~+85°C.
DURABILITY:2000 CYCLES

MICRO SD-PIN	
P1N NO.	PIN NAME
P1	DAT 2
P2	CD/DAT 3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT 0
P8	DAT 1

RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准	 SCALE 比例 参考	UNLESS OTHERWISE SPECIFIED TOLERANCES U.S. METRIC X XX +/- 0.15 0.15 100 +/- 0.10 0.10 FRACTIONS +/- 0.15 0.15 ANGLES +/- 0.5	PART NAME 品名 MICRO SD CARD HOLDER OF NANO SIM +MICRO SD CONNECTOR 3 IN 1 TYPE CONTACT AREA:GOLD 10U" PLATING SOLDER AREA:GOLD 3U" PLATING BLACK COLOR REEL PACKING ROHS
DWG. 製圖	Betty	UNIT 單位 M M	PART NO. 料號 C0675-TB3BR0000R
DATE 制表日	2023/11/22	PAGE 張數 4 OF 4	
		REV. 版次 A	